

BRS2AFQ~BRS2MFQ

Rev.A Jun.-2024



DATA SHEET

50V~1000V

2.0A SMAF

- Note:
- 1 Measured at 1 MHz and applied reverse voltage of 4 V D.C
 - 2 P.C.B. mounted with 2.0 X 2.0" (5 X 5 cm) copper pad areas.

Parameter	Symbol	Test condition	Rating	Unit
Maximum Instantaneous Forward Voltage	V_F	$I_F=2.0A$	1.1	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_a=25$ $T_a=125$	5.0	uA

/ Electrical Characteristic Curve

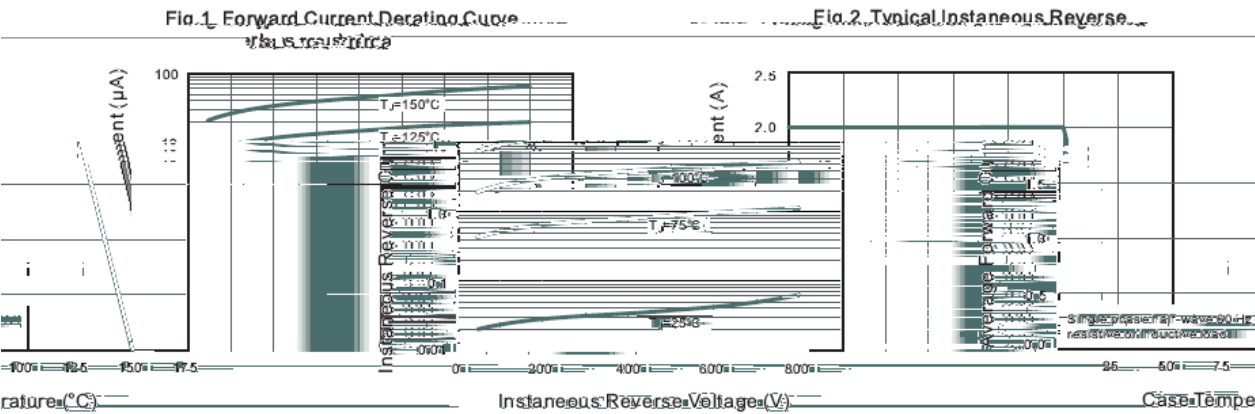


Fig.3 Typical Forward

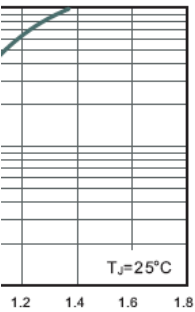


Fig.4 Typical Junction Capacitance

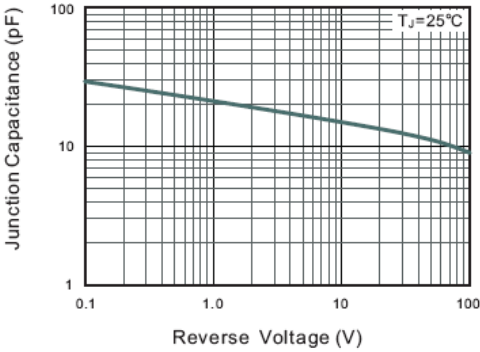


Fig.5 Maximum Non

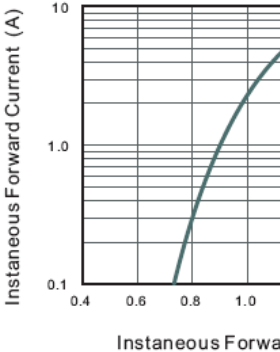
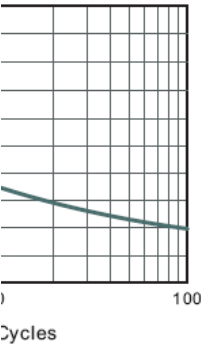
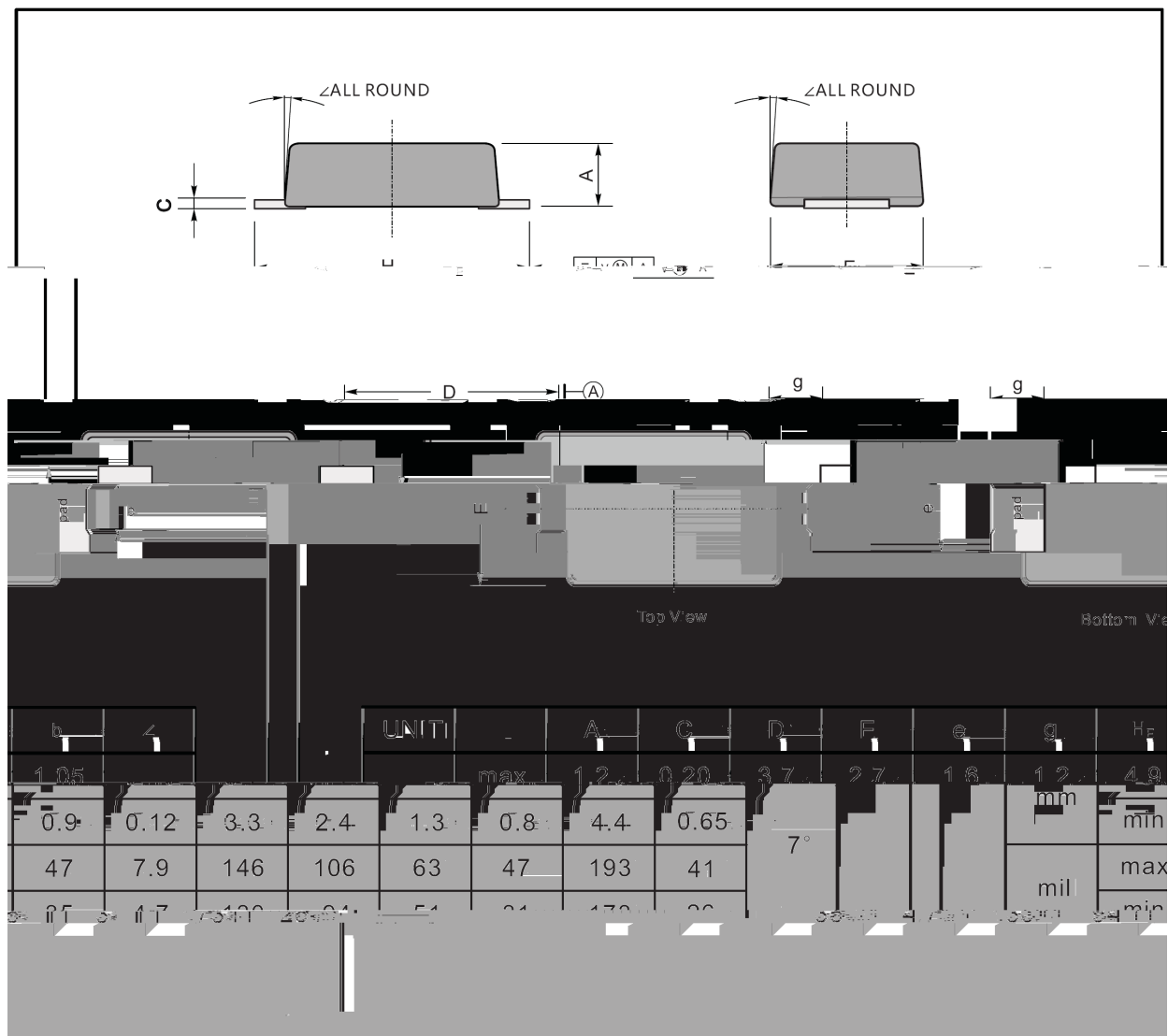


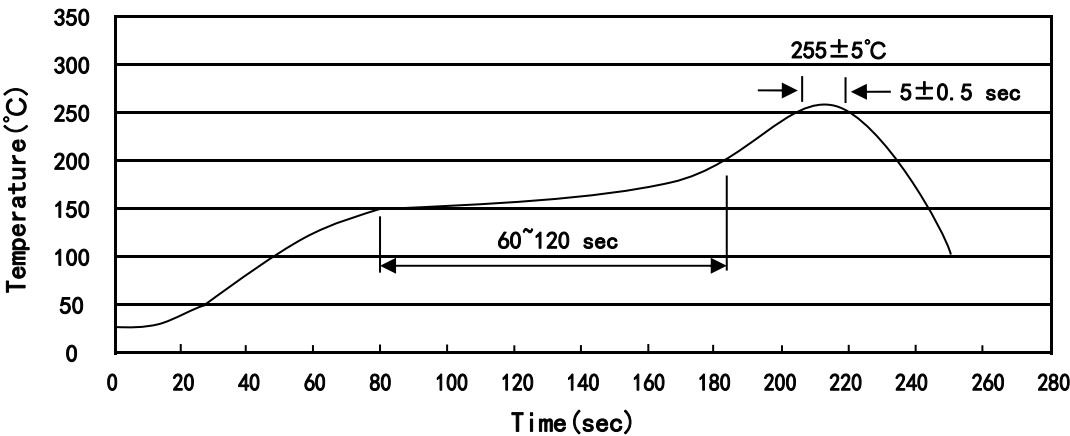
Fig.6 Repetitive Peak



/ Package Dimensions



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 200

60 120sec;

1.Preheating:150~200 , Time:60~120sec.
- 2

255±5

5±0.5sec;

2.Peak Temp.:255±5 , Duration:5±0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMAF	3,000	5	15,000	6	90,000	7 ×12	185×180×105	390×385×205

/ Notices